

FIG.11

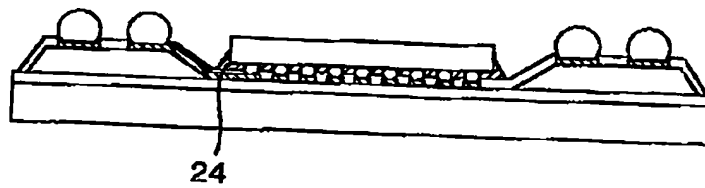


FIG.12

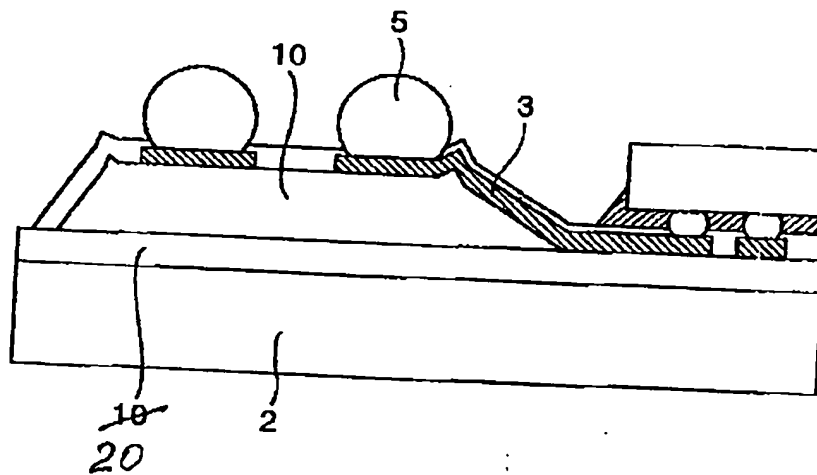


FIG.23A

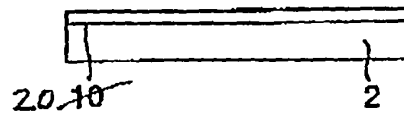


FIG.23B

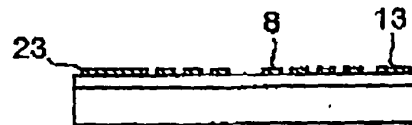


FIG.23C

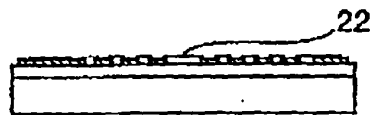


FIG.23D

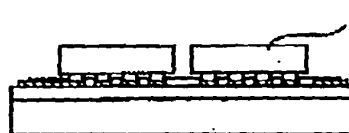


FIG.23E

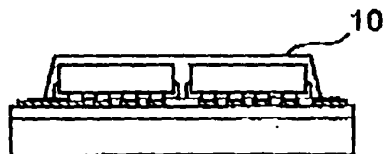


FIG.23F

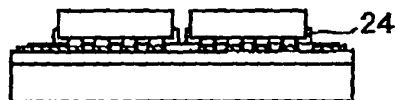


FIG.23G

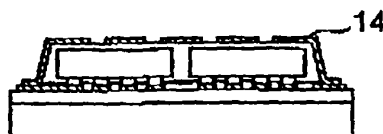


FIG.27

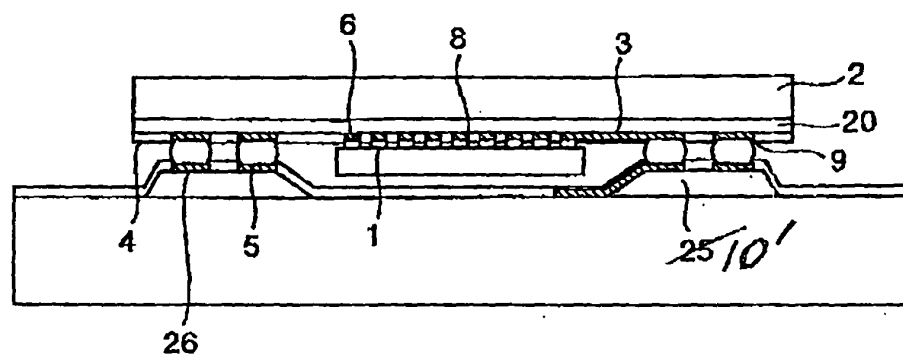


FIG.28

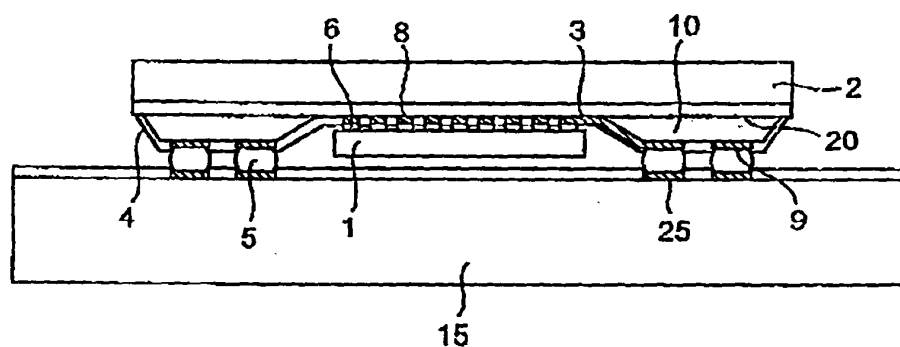
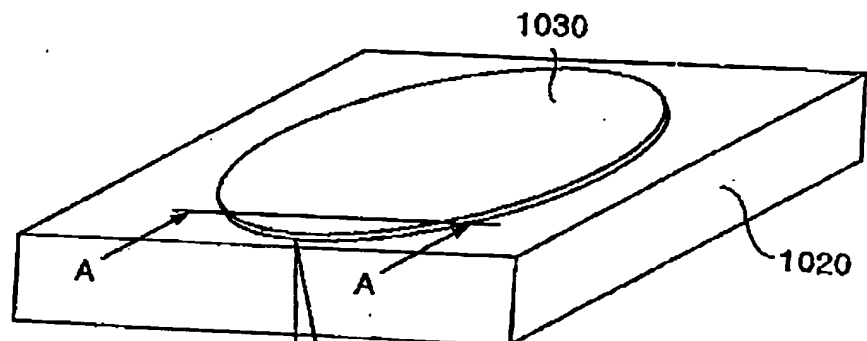


FIG.39A

RELEASED BY
EJECTER PIN

THE STRESS COMPLIANT
LAYER FORMED SILICON
SUBSTRATE

FIG.39B



A MAGNIFIED VIEW OF
A-A CROSS SECTION

FIG.39C

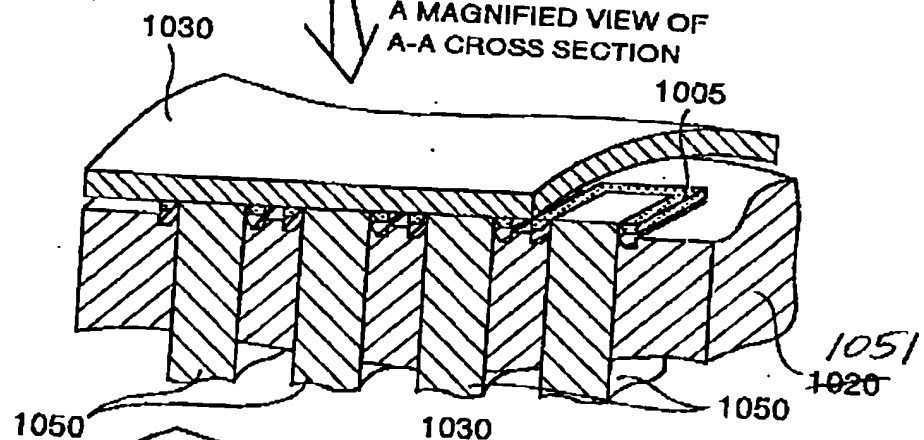


FIG.39D

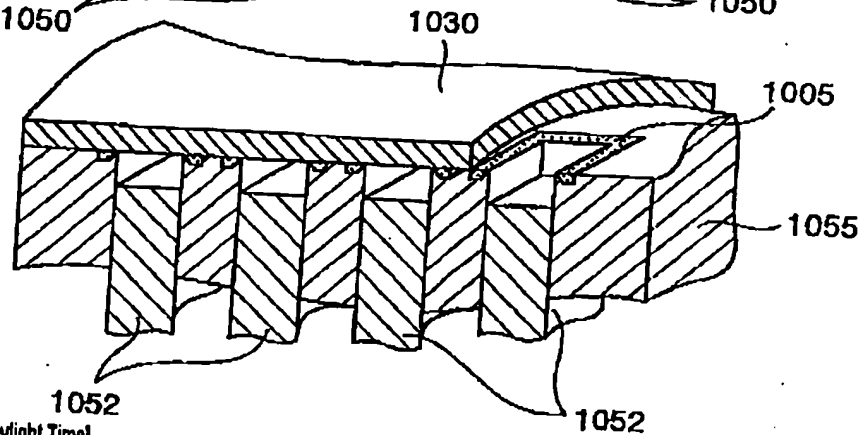


FIG.42A

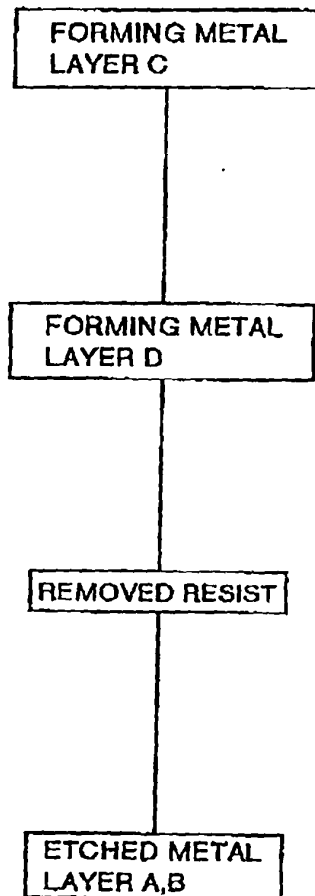


FIG.42B

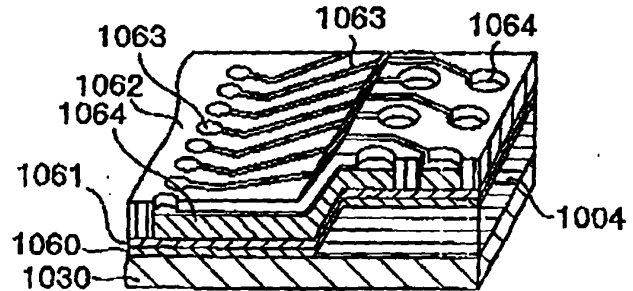


FIG.42C

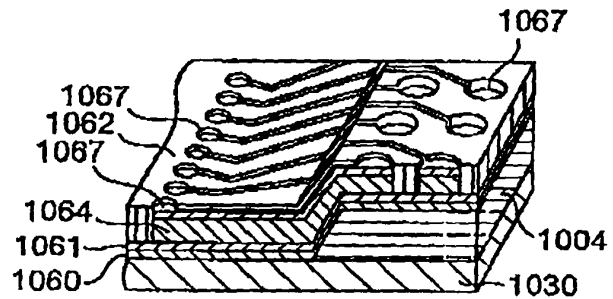


FIG.42D

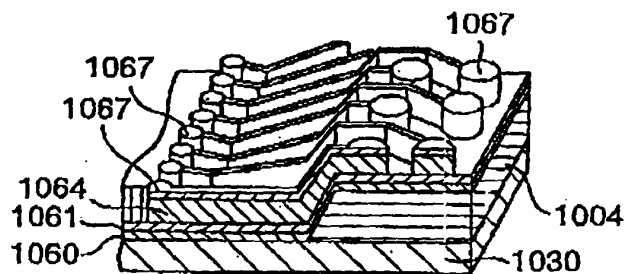


FIG.42E

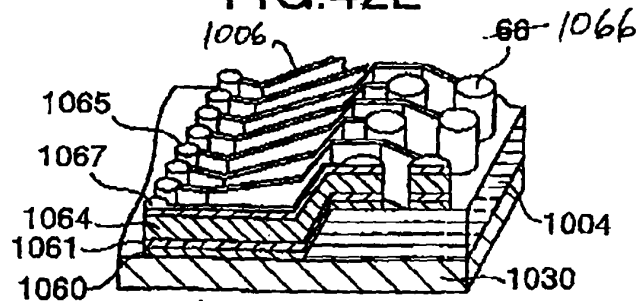


FIG.45B

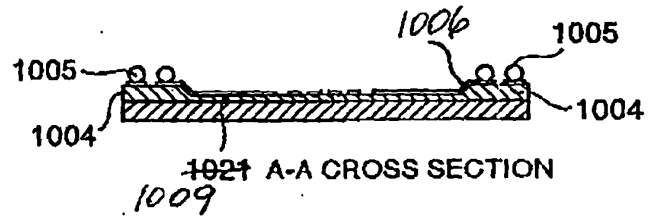


FIG. 46A

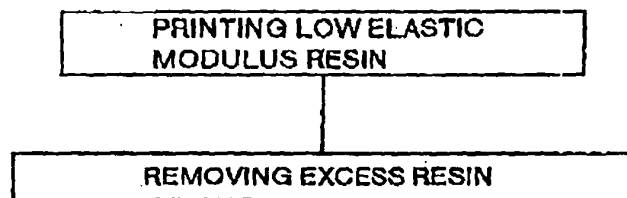


FIG.46B

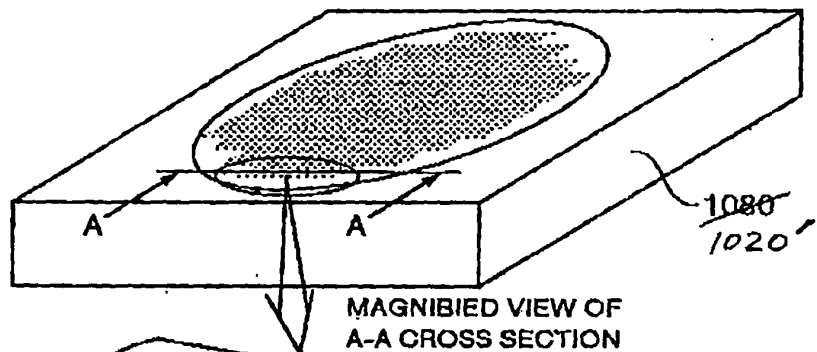


FIG.46C

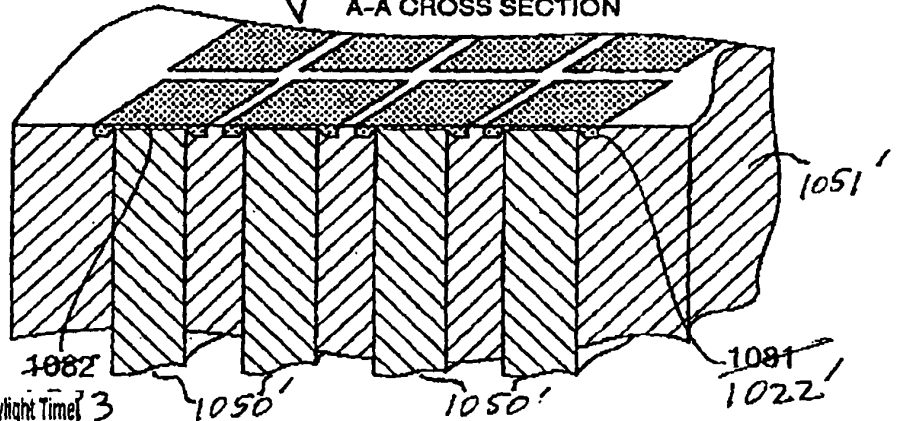


FIG.47A

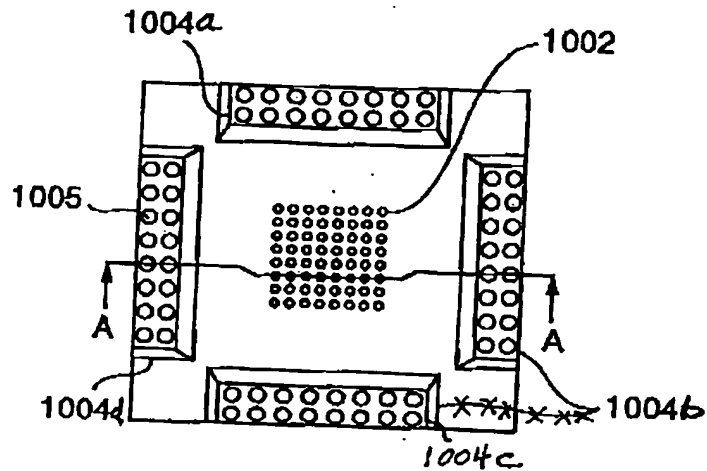


FIG.47B



FIG.48

